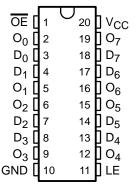
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- **Function and Pinout Compatible With FCT** and F Logic
- Reduced V_{OH} (Typically = 3.3 V) Versions of Equivalent FCT Functions
- **Edge-Rate Control Circuitry for** Significantly Improved Noise Characteristics
- I_{off} Supports Partial-Power-Down Mode Operation
- **ESD Protection Exceeds JESD 22**
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- **Matched Rise and Fall Times**
- Fully Compatible With TTL Input and **Output Logic Levels**
- **3-State Outputs**
- CY54FCT373T
 - 32-mA Output Sink Current
 - 12-mA Output Source Current
- CY74FCT373T
 - 64-mA Output Sink Current
 - 32-mA Output Source Current

CY54FCT373T . . . D PACKAGE CY74FCT373T...Q OR SO PACKAGE (TOP VIEW)



description

The 'FCT373T devices consist of eight latches with 3-state outputs for bus-organized applications. When the latch-enable (LE) input is high, the flip-flops appear transparent to the data. Data that meets the required setup times are latched when LE transitions from high to low. Data appears on the bus when the output-enable $(\overline{\sf OE})$ input is low. When $\overline{\text{OE}}$ is high, the bus output is in the high-impedance state. In this mode, data can be entered into the latches.

These devices are fully specified for partial-power-down applications using Ioff. The Ioff circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



ORDERING INFORMATION

TA	PACI	(AGE†	SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	QSOP - Q	Tape and reel	4.7	CY74FCT373CTQCT	FCT373C	
	SOIC - SO	Tube	4.7	CY74FCT373CTSOC	FCT373C	
–40°C to 85°C	3010 - 30	Tape and reel	4.7	CY74FCT373CTSOCT	FC1373C	
	QSOP - Q	Tape and reel	5.2	CY74FCT373ATQCT	FCT373A	
-40 C to 65 C	SOIC - SO	Tube	5.2	CY74FCT373ATSOC	FCT373	
	3010 - 30	Tape and reel	5.2	CY74FCT373ATSOCT	FC13/3	
	SOIC - SO	Tube	8	CY74FCT373TSOC	507070	
	3010 - 30	Tape and reel	8	CY74FCT373TSOCT	FCT373	
–55°C to 125°C	CDIP – D	Tube	5.6	CY54FCT373ATDMB		

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

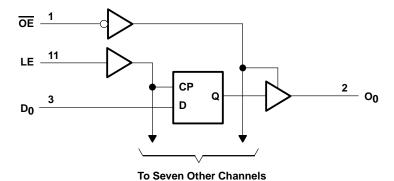
	INPUTS		OUTPUT
OE	LE	D	0
L	Н	Н	Н
L	Н	L	L
L	L	Χ	Q_0
Н	X	Χ	z

H = High logic level, L = Low logic level,

X = Don't care, Z = High-impedance state,

 Q_n = Previous state of flip flops (Q_{n-1})

logic diagram (positive logic)





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absolute maximum rating over operating free-air temperature range (unless otherwise noted)†

Supply voltage range to ground potential	-0.5 V to 7 V
DC input voltage range	\dots –0.5 V to 7 V
DC output voltage range	\dots –0.5 V to 7 V
DC output current (maximum sink current/pin)	120 mA
Package thermal impedance, θ _{JA} (see Note 1): Q package	68°C/W
SO package	58°C/W
Ambient temperature range with power applied, T _A	–65°C to 135°C
Storage temperature range, T _{Stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 2)

		CY54FCT373T			CY7	74FCT37	3T	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	Oitiii
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
ІОН	High-level output current			-12			-32	mA
loL	Low-level output current			32			64	mA
T _A	Operating free-air temperature	-55		125	-40		85	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.



NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

CY54FCT373T, CY74FCT373T 8-BIT LATCHES WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER		TEOT CONDITIO	NO.	CY	54FCT37	73T	CY	74FCT37	'3T	UNIT	
PARAMETER		TEST CONDITIO	ONS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNII	
Voc	V _{CC} = 4.5 V,	I _{IN} = -18 mA			-0.7	-1.2				V	
VIK	$V_{CC} = 4.75 \text{ V},$	I _{IN} = -18 mA						-0.7	-1.2	V	
	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -12 \text{ mA}$		2.4	3.3						
Voн	V _{CC} = 4.75 V	$I_{OH} = -32 \text{ mA}$					2			V	
	VCC = 4.75 V	$I_{OH} = -15 \text{ mA}$					2.4	3.3			
Voi	$V_{CC} = 4.5 \text{ V},$	I_{OL} = 32 mA			0.3	0.55				V	
VOL	$V_{CC} = 4.75 \text{ V},$	$I_{OL} = 64 \text{ mA}$						0.3	0.55		
V_{hys}	All inputs				0.2			0.2		V	
١,	$V_{CC} = 5.5 \text{ V},$	VIN = VCC				5				μΑ	
łį	$V_{CC} = 5.25 \text{ V},$	VIN = VCC							5	μΛ	
¹ıн	$V_{CC} = 5.5 \text{ V},$	$V_{1N} = 2.7 \text{ V}$				±1				μΑ	
	$V_{CC} = 5.25 \text{ V},$	V _{IN} = 2.7 V							±1	,	
1	$V_{CC} = 5.5 \text{ V},$	V _{IN} = 0.5 V				±1				μΑ	
IIL	$V_{CC} = 5.25 \text{ V},$	V _{IN} = 0.5 V							±1	μΛ	
IOZH	$V_{CC} = 5.5 \text{ V},$	V _{OUT} = 2.7 V				10				μΑ	
10ZH	$V_{CC} = 5.25 \text{ V},$	V _{OUT} = 2.7 V							10	μΛ	
IOZL	$V_{CC} = 5.5 \text{ V},$	V _{OUT} = 0.5 V				-10				μΑ	
'OZL	$V_{CC} = 5.25 \text{ V},$	V _{OUT} = 0.5 V							-10	μι	
los‡	$V_{CC} = 5.5 \text{ V},$	$V_{OUT} = 0 V$		-60	-120	-225				mA	
105+	$V_{CC} = 5.25 \text{ V},$	V _{OUT} = 0 V					-60	-120	-225	ША	
l _{off}	$V_{CC} = 0 V$,					±1			±1	μΑ	
Icc	$V_{CC} = 5.5 \text{ V},$	$V_{IN} \le 0.2 V$	$V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.1	0.2				mA	
'00			$V_{IN} \ge V_{CC} - 0.2 \text{ V}$					0.1	0.2		
ΔlCC		$V_{CC} = 5.5 \text{ V}, V_{IN} = 3.4 \text{ V}$, $f_1 = 0$, Outputs open			0.5	2				mA	
Δi()($V_{CC} = 5.25 V, V$	$IN = 3.4 \text{ V}$, $f_1 = 0$, C	Outputs open					0.5	2	ША	

[†] Typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, IOS tests should be performed last.

[§] Per TTL-driven input (V_{IN} = 3.4 V); all other inputs at V_{CC} or GND

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

DADAMETED		TEST CONDITION	10	CY	54FCT3	73T	CY	74FCT37	'3T	LINUT
PARAMETER		TEST CONDITION	3	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT
loop¶		tputs open, iing at 50% duty cycle, IN ≥ V _{CC} – 0.2 V	OE = GND,		0.06	0.12				mA/
ICCD¶	One input switch	CC = 5.25 V, Outputs open, ne input switching at 50% duty cycle, $\overline{OE} = \text{GND}$, $N \le 0.2 \text{ V or V}_{\text{IN}} \ge \text{V}_{\text{CC}} - 0.2 \text{ V}$						0.06	0.12	MHz
Vcc =	V _{CC} = 5.5 V,	One bit switching at f ₁ = 10 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.7	1.4				
	Outputs open,	at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$		1	2.4				
	OE = GND, LE = V _{CC}	Eight bits switching at f ₁ = 2.5 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		1.3	2.6				
lc#		at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$		3.3	10.6				mA
ıC	V _{CC} = 5.25 V,	One bit switching at f ₁ = 10 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$					0.7	1.4	IIIA
	Outputs open,	at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$					1	2.4	
	OE = GND, LE = V _{CC}	Eight bits switching at f ₁ = 2.5 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$					1.3	2.6	
		at 50% duty cycle	V _{IN} = 3.4 V or GND					3.3	10.6	
C _i					6	10		6	10	pF
Co					8	12		8	12	pF

[†] Typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

Where:

 $\begin{array}{ll} I_C & = \mbox{Total supply current} \\ I_{CC} & = \mbox{Power-supply current with CMOS input levels} \end{array}$

 ΔI_{CC} = Power-supply current for a TTL high input ($V_{IN} = 3.4 \text{ V}$)

D_H = Duty cycle for TTL inputs high N_T = Number of TTL inputs at D_H

I_{CCD} = Dynamic current caused by an input transition pair (HLH or LHL)

= Clock frequency for registered devices, otherwise zero

= Input signal frequency

= Number of inputs changing at f₁

All currents are in milliamperes and all frequencies are in megahertz.

|| Values for these conditions are examples of the I_{CC} formula.



This parameter is derived for use in total power-supply calculations.

 $^{^{\#}}$ IC = ICC + \triangle ICC \times D_H \times N_T + ICCD ($f_0/2 + f_1 \times N_1$)

CY54FCT373T, CY74FCT373T 8-BIT LATCHES WITH 3-STATE OUTPUTS

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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		CY54FC	T373T	CY54FCT	UNIT		
		MIN MAX		MIN	MAX	CIVIT	
t _W	Pulse duration, LE high	6		6		ns	
t _{su}	Setup time, data before LE↑	2		2		ns	
th	Hold time, data after LE↑	1.5		1.5		ns	

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		CY74FC	CY74FCT373T		373AT	CY74FCT	UNIT	
		MIN	MAX	MIN	MAX	MIN	MAX	UNII
t _W	Pulse duration, LE high	6		5		5		ns
t _{su}	Setup time, data before LE↑	2		2		2		ns
th	Hold time, data after LE↑	1.5		1.5		1.5		ns

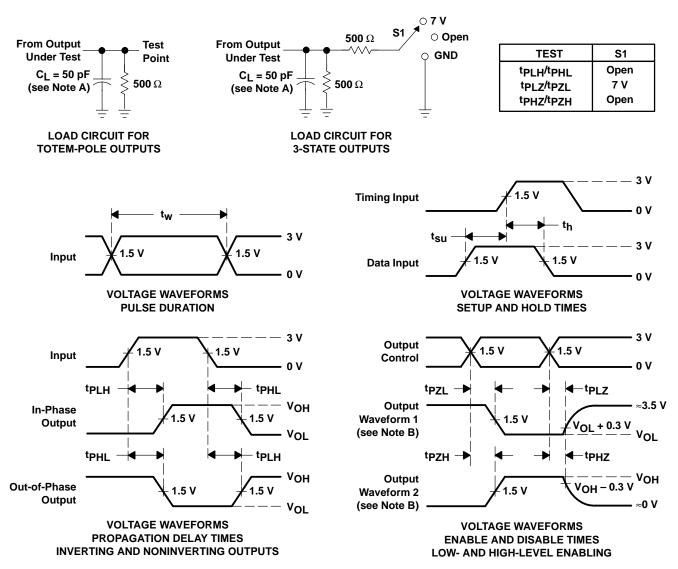
switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM	то	CY54FCT	UNIT		
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	ONIT	
t _{PLH}	D	0	1.5	5.6	ns	
^t PHL	D	O	O 1.5			
t _{PLH}	LE	0	2	9.8	ns	
^t PHL	LL	O	2	9.8	115	
^t PZH	ŌĒ	0	1.5	7.5	nc	
^t PZL	OE .	0	1.5	7.5	ns	
^t PHZ	OE 0		1.5	6.5	ns	
tPLZ	JE.	J	1.5	6.5	115	

switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM	то	CY74FC	T373T	CY74FCT	373AT	CY74FCT	373CT	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
t _{PLH}	D	0	1.5	8	1.5	5.2	1.5	4.7	ns
^t PHL	D	0	1.5	8	1.5	5.2	1.5	4.7	115
t _{PLH}	LE	0	2	13	2	8.5	2	5.5	ns
tpHL	LC	U	2	13	2	8.5	2	5.5	115
^t PZH	ŌĒ	0	1.5	12	1.5	6.5	1.5	5.5	ns
t _{PZL}	OE .		1.5	12	1.5	6.5	1.5	5.5	115
^t PHZ	ŌĒ	0	1.5	7.5	1.5	5.5	1.5	5	ns
^t PLZ	OE	0	1.5	7.5	1.5	5.5	1.5	5	115





PARAMETER MEASUREMENT INFORMATION

NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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PACKAGING INFORMATION

Orderable part number	Status	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
5962-9221701MRA	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9221701MR A
5962-9221702MRA	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9221702MR A CY54FCT373ATDM B
5962-9221703M2A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9221703M2A
CY54FCT373ATDMB	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9221702MR A CY54FCT373ATDM B
CY74FCT373ATQCT	Active	Production	SSOP (DBQ) 20	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT373A
CY74FCT373ATQCT.B	Active	Production	SSOP (DBQ) 20	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT373A
CY74FCT373ATQCTG4	Active	Production	SSOP (DBQ) 20	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT373A
CY74FCT373ATQCTG4.B	Active	Production	SSOP (DBQ) 20	2500 LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT373A
CY74FCT373ATSOC	Active	Production	SOIC (DW) 20	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT373A
CY74FCT373ATSOC.B	Active	Production	SOIC (DW) 20	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT373A
CY74FCT373TSOC	Active	Production	SOIC (DW) 20	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT373
CY74FCT373TSOC.B	Active	Production	SOIC (DW) 20	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT373

⁽¹⁾ Status: For more details on status, see our product life cycle.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.



PACKAGE OPTION ADDENDUM

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(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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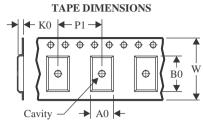
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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT373ATQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT373ATQCTG4	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

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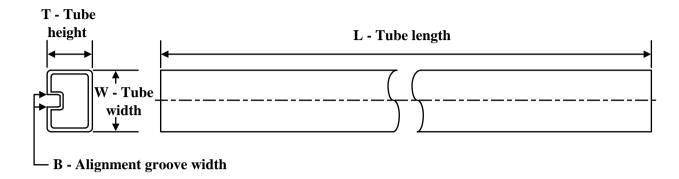
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CY74FCT373ATQCT	SSOP	DBQ	20	2500	353.0	353.0	32.0
CY74FCT373ATQCTG4	SSOP	DBQ	20	2500	353.0	353.0	32.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9221703M2A	FK	LCCC	20	55	506.98	12.06	2030	NA
CY74FCT373ATSOC	DW	SOIC	20	25	507	12.83	5080	6.6
CY74FCT373ATSOC.B	DW	SOIC	20	25	507	12.83	5080	6.6
CY74FCT373TSOC	DW	SOIC	20	25	507	12.83	5080	6.6
CY74FCT373TSOC.B	DW	SOIC	20	25	507	12.83	5080	6.6

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